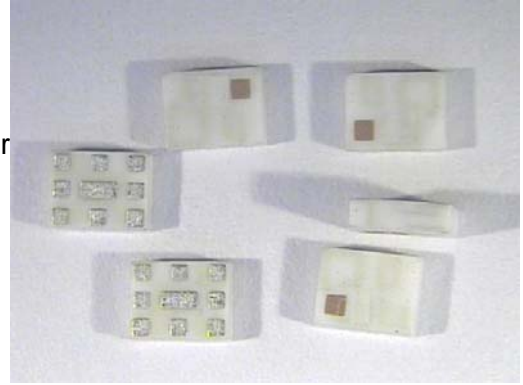


TP 2520 Series

Multilayer Chip Triplexers



Features

- ❖ Monolithic structure including a low-pass filter \ band-pass filter and high-pass filter with loss pole at adjacent passband.
- ❖ RoHS compliant

Applications

- ❖ Wireless communication

Target Specifications

Part Number	Passband (MHz)	Insertion Loss (dB)	VSWR	Attenuation (dB)
TP2520-A091824QS	824~894	1.0 max.	2.0 Max.	30 min. @ 1710 ~ 1880MHz 15 min. @ 2300 ~ 2400MHz
	1710~1880	1.0 max.	2.0 Max.	15 min. @ 824 ~ 894MHz 15 min. @ 2300 ~ 2400MHz
	2300~2400	1.0 max.	2.0 Max.	15 min. @ 824 ~ 894MHz 15 min. @ 1710 ~ 1880MHz

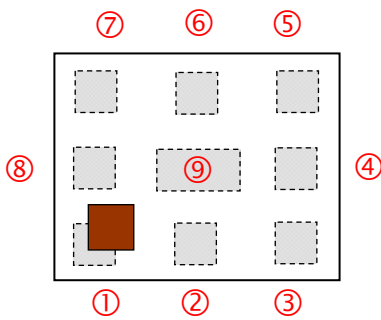
Q'ty/Reel (pcs) : 3,000
 Operating Temperature Range : -40 ~ +85 °C
 Storage Temperature Range : -40 ~ +85 °C,
 Storage Period : 12 months max.
 Power Capacity : 2W max.

Part Number

TP 2520 - A 091824 QS □ /LF
 ① ② ③ ④ ⑤ ⑥ ⑦

① Type	TP : Triplexer	② Dimensions (L x W)	2.5 x 2.0 mm
③ Material Code	A	④ Frequency Range	091824=900MHz /1800MHz/2400MHz
⑤ Specification Code	QS	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	/LF=lead-free		

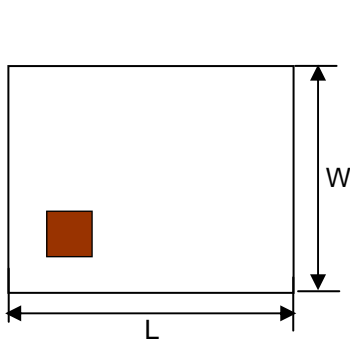
Terminal Configuration



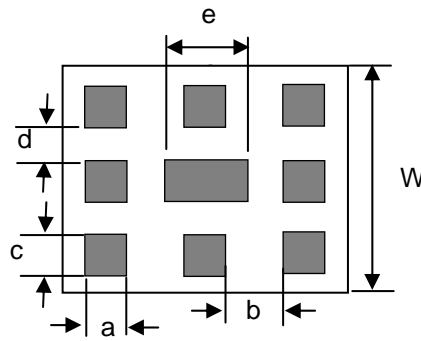
<Top View>

No.	Terminal Name	No.	Terminal Name
①	GND	⑥	Middle band
②	Ant	⑦	GND
③	GND	⑧	Low band
④	High band	⑨	GND
⑤	GND		

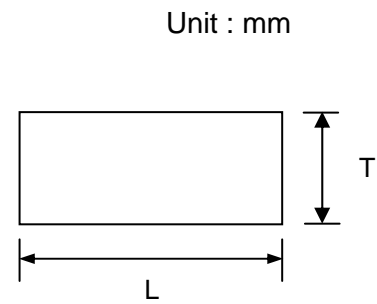
Dimensions and Recommended PC Board Pattern



<Top View>



<Bottom View>



<Side View>

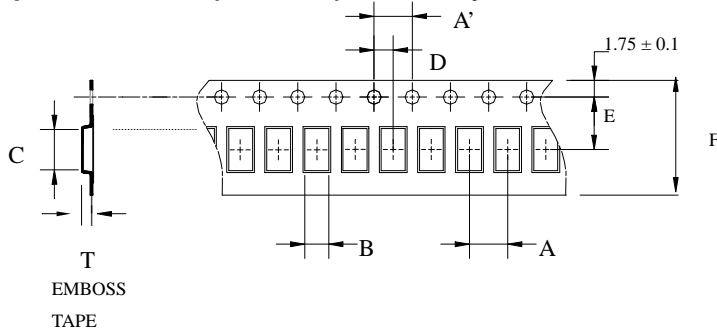
Mark	L	W	T	a	b	c	d	e
Dimensions	2.5 ±	2.0 ±	0.9	0.4 ±	0.55 ±	0.4 ±	0.3 ±	0.9 ±
	0.2	0.2	max	0.1	0.15	0.1	0.1	0.15

Notes

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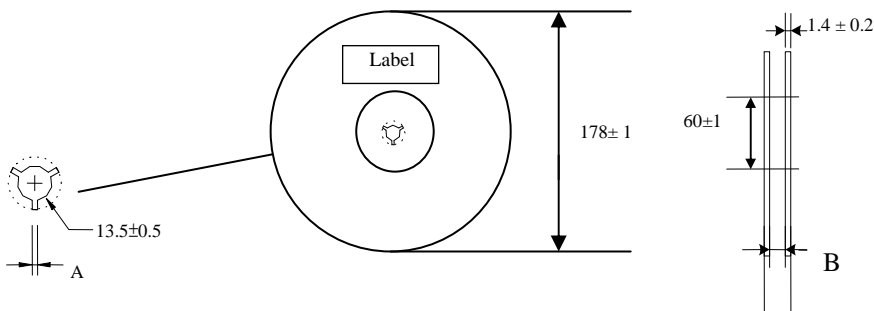
Taping Specifications

❖Tape Dimensions (Unit: mm) & Quantity



Type	A	A'	B	C	D	E	F	T	Quantity/reel	Tape material
2520	4.0±	4.0±	2.35±	2.80±	2.0±	3.5±	8.0±	1.15±	3,000pcs	Plastic (Embossed)
	0.1	0.1	0.1	0.1	0.1	0.1	0.1	0.10		

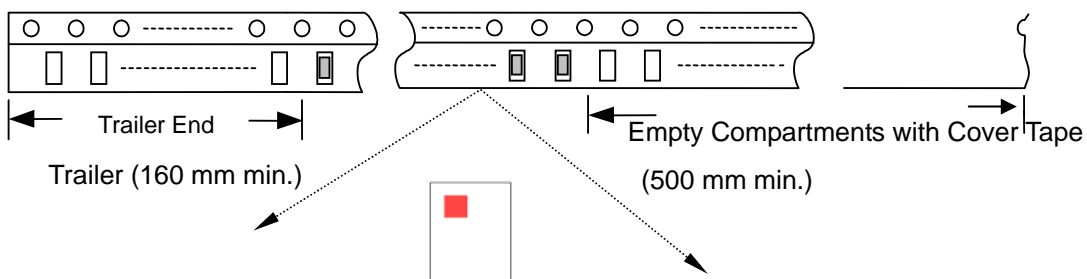
❖Reel Dimensions (Unit: mm)



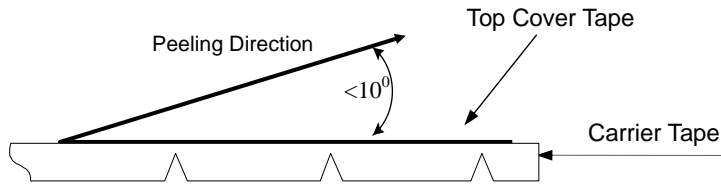
Label: Customer's Name,
ACX P/N, Q'ty, Date,
ACX Corp.

Type	A	B
2520	2.3±0.5	9.0±0.3

❖Leader and Trailer Tape



❖ **Peel-off Force**



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of 300 ± 10 mm/min .

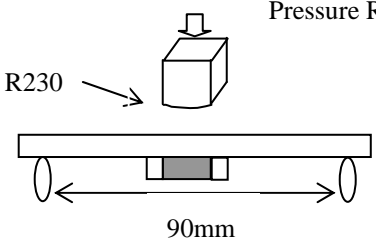
❖ **Storage Conditions**

- (1) Temperature: $+5 \sim 35^{\circ}\text{C}$, relative humidity (RH): 45~75%.
- (2) Non-corrosive environment.

Notes

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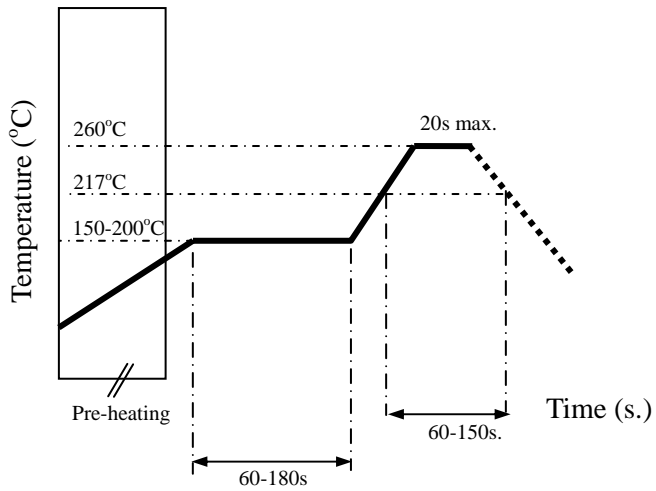
Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	<ol style="list-style-type: none"> No apparent damage More than 95% of the terminal electrode shall be covered with new solder 	<ol style="list-style-type: none"> Preheat: $120 \pm 5^\circ\text{C}$ Solder: $245 \pm 5^\circ\text{C}$ for 5 ± 1 sec
Soldering strength (Termination Adhesion)	<ol style="list-style-type: none"> 1kg minimum 	<ol style="list-style-type: none"> Solder specimen onto test jig. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction.
Deflection (Substrate Bending)	<ol style="list-style-type: none"> No apparent damage 	<ol style="list-style-type: none"> Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile. Apply a bending force of 2mm deflection 
Heat/Humidity Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $85 \pm 2^\circ\text{C}$ Humidity: 90% ~ 95% RH Duration: 1000 ± 48hrs Recovery: 1-2hrs
Thermal shock (Temperature Cycle)	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> One cycle/step 1 : $125 \pm 5^\circ\text{C}$ for 30 min step 2 : $-40 \pm 5^\circ\text{C}$ for 30 min No of cycles : 100 Recovery: 1-2 hrs
Low Temperature Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $-40 \pm 5^\circ\text{C}$ Duration: 500 ± 24hrs Recovery: 1-2hrs

Soldering Conditions

❖ Typical Soldering Profile for Lead-free Process

Reflow Soldering :



Notes

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